



RESONATOR

ZTB614P

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7/F., New Trend Centre, 704 Prince Edward Road East, San Po Kong, Kowloon, Hong Kong.

1 SCOPE

This specification shall cover the characteristics of the ceramic resonator with the type ZTB614P.

2 PART NO.

PART NUMBER	CUSTOMER PART NO	SPECIFICATION NO
ZTB614P		

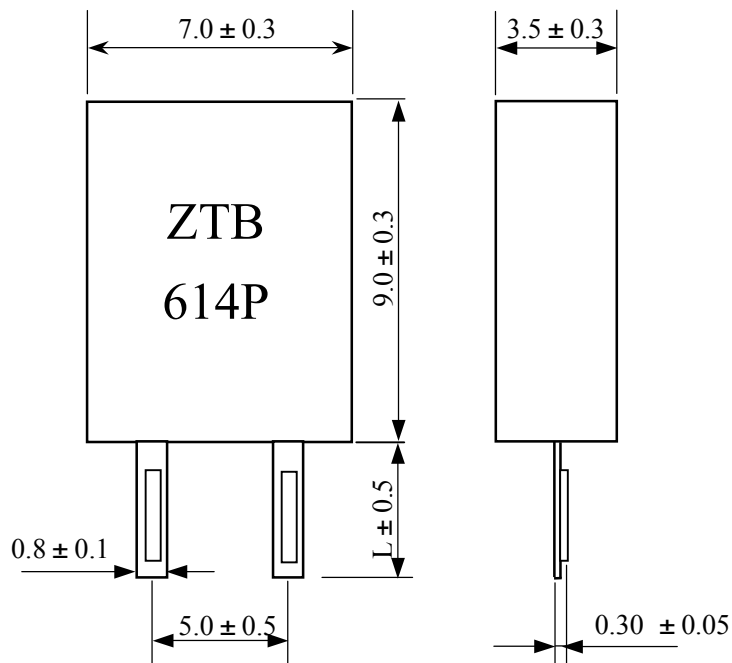
3 OUTLINE DRAWING AND DIMENSIONS

3.1 Appearance: No visible damage and dirt.

3.2 Construction: Leads are soldered on electrode and body is molded by resin.

Dimensions

3.3 Except the chip(ceramic element, ceramic base, capacitance slice), the materials don't contain lead.



L:6/4 mm



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4 RATING AND ELECTRICAL SPECIFICATIONS

4.1 RATING

Items	Content
Withstanding Voltage (V)	50 (DC , 1min)
Insulation Resistance Ri, (M) min.	100 (100V , 1min)
Operating Temperature Range	-20 ~ +80
Storage Temperature Range	-40 ~ +85

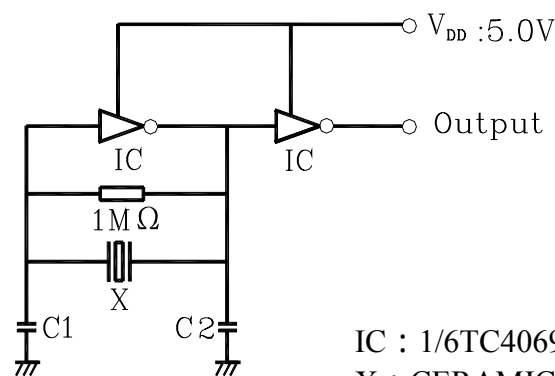
4.2 ELECTRICAL SPECIFICATIONS

Items	Content
Oscillation Frequency Fosc (kHz)	614
Frequency Accuracy (kHz)	± 2.0
Resonant Impedance Ro (Ω) max	30
Temperature Coefficient of Oscillation Frequency (%) max	± 0.3 (Oscillation Frequency drift , -25 ~ +85)
Rating Voltage UR (V) max	6VDC 15Vp-p
Aging Rate (%) max	± 0.3 (For Ten Years)

5 MEASUREMENT

5.1 Measurement Conditions: Parts shall be measured under a condition (Temp. : 20 ± 15 , Humidity : $65 \pm 20\%$ R.H.) unless the standard condition (Temp. : 25 ± 3 , Humidity : $65 \pm 5\%$ R.H.) is regulated to measure.

5.2 Test Circuit



IC : 1/6TC4069UBP×2
X : CERAMIC RESONATOR
C1,C2 : 100,100 pF



6 PHYSICAL AND ENVIRONMENTAL CHARACTERISTICS

No.	Item	Condition of Test	Performance Requirements
6.1	Humidity	Subject the resonator at $+40 \pm 2$ and 90%-95% R.H. for 96h, resonator shall be measured after being placed in natural conditions for 1h.	It shall fulfill the specifications in Table 1.
6.2	High Temperature Exposure	Subject the resonator to $+85 \pm 5$ for 96h, resonator shall be measured after being placed in natural conditions for 1h.	It shall fulfill the specifications in Table 1.
6.3	Low Temperature Exposure	Subject the resonator to -25 ± 5 for 96h, resonator shall be measured after being placed in natural conditions for 1h.	It shall fulfill the specifications in Table 1.
6.4	Temperature Cycling	Subject the resonator to -25 for 30 min. followed by a high temperature of $+85$ for 30 min. Cycling shall be repeated 5 times. Resonator shall be measured after being placed in natural conditions for 1h.	It shall fulfill the specifications in Table 1.
6.5	Vibration	Subject the resonator to vibration for 2h each in x y and z axis with the amplitude of 1.5mm, the frequency shall be varied uniformly between the limits of 10Hz-55Hz and then resonator shall be measured.	It shall fulfill the specifications in Table 1.
6.6	Mechanical Shock	Resonator shall be measured after 3 times' random dropping from the height of 70cm on concrete floor.	No visible damage and it shall fulfill the specifications in Table 1.
6.7	Resistance to Soldering Heat	Lead terminals are immersed up to 2 mm from resonator's body in soldering bath of 260 ± 5 for $5s \pm 1s$ and then resonator shall be measured after being placed in natural conditions for 1h	It shall fulfill the specifications in Table 1.
6.8	Solderability	Lead terminals are immersed up to 2mm from resonator's body in soldering bath of 250 ± 5 for $2s \pm 0.5s$.	More than 95% of the terminal surface of the resonator shall be covered with fresh solder.

(To be continued)



6 PHYSICAL AND ENVIRONMENTAL CHARACTERISTICS

No	Item	Condition of Test	Performance Requirements
6.9	Terminal Strength	Force of 5N is applied to each lead in axial direction for $10s \pm 1s$.	No visible damage and it shall fulfill the specifications in Table 1.
6.9.1	Terminal Pulling	When force of 5N is applied to each lead in axial direction, the lead shall be folded up 90° from the axial direction and folded back to the axial direction. The speed of folding shall be each 3s.	
6.9.2	Terminal Bending		

Table 1

Item	Specification after test
Oscillation Frequency Change $F_{osc}/F_{osc} (\%) \text{ max}$	± 0.3
Note : The limits in the above table are referenced to the initial measurements.	



7 PACKAGE

To protect the products in storage and transportation , it is necessary to pack them(outer and inner package).On paper pack, the following requirements are requested.

7.1 Section of package

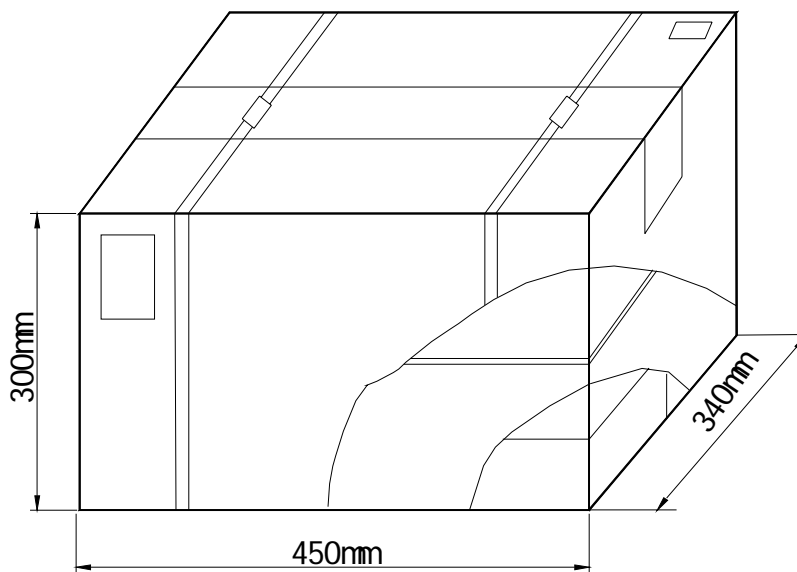
Package is made of corrugated paper with thickness of 0.8cm.Package has 2 inner packages, each has 20 inner boxes (each box for plastic bag).

7.2 Quantity of package

- Per plastic bag 500 pieces
 - Per inner box 2 plastic bags
 - Per inner package 20 inner boxes
 - Per package 2 inner packages
- (40000 pieces of piezoelectric ceramic part)

7.3 Dimensions and Mark

At the end of package, the warning (moisture proof, upward put) should be stick to it(see below)

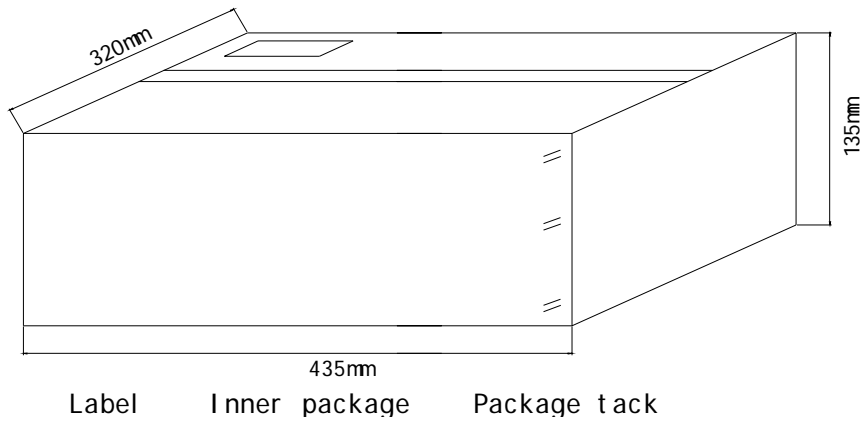


Bel t (2. 9m)	Label (1)	Package(1)
Cer t i f i c a t e o f	Adhesi ve	Box(2)
proval (1)	tape(1. 2m)	I nner box(40)

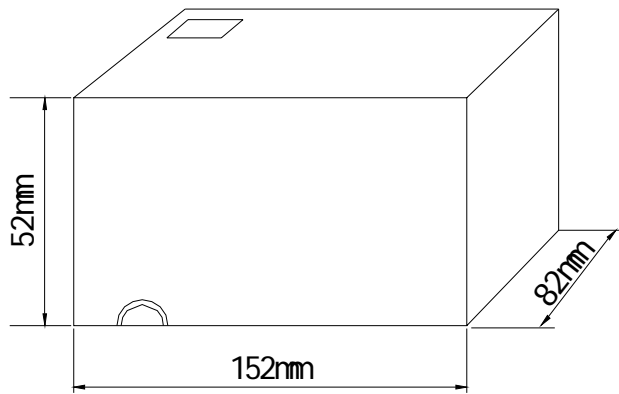


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7.4 Inner package



7.5 Inner box Dimensions



Pars shall be packaged in box with hold down tape upside. Part No., quantity and lot No.



8 OTHER

8.1 Caution of use

8.1.1 Do not clean or wash the component for it is not hermetically sealed.

8.1.2 Don't be close to fire

8.1.3 Don't apply excess mechanical stress to the component.

8.1.4 Don't bend terminals of the component

8.1.5 This specification mentions the quality of the component as a single unit. Please insure the component is thoroughly evaluated in your application circuit.

8.1.6 Do not pass through the re-flow. Handwork jointing or wave crest jointing is allowed.

8.1.7 It may be influential to the component solderability if the component is used beyond 6 months.

9.2 Notice

9.2.1 Please return one of this specification after your signature of acceptance.

9.2.2 When something gets doubtful with this specifications, we shall jointly work to get an agreement.



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